



PCN# : P53AAAB
Issue Date : Mar. 27, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jun. 25, 2015

Expected First Date Code of Changed Product :1526

Description of Change (From) :
Wafer Fabrication site subcontractor TSMC Taiwan, 8"

Description of Change (To) :
Wafer Fabrication site subcontractor SSMC, Singapore, 8"

Reason for Change:
Increase the wafer supply capacity and flexibility.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

| Qualification Plan | Device | Package | Process | No. of Lots |
|--------------------|------------------|-----------|--|-------------|
| Q20140398 | FPF2280BUCX_F130 | UCBBU-012 | SSMC C18BCD gen 2 Amkor T5/T3& ASE/Cebu | 3 |

| Test Description: | Condition: | Standard : | Duration: | Results: |
|---|-------------------|-------------|------------|----------|
| Highly Accelerated Stress Test | 110C, 85%RH, 5.5V | JESD22-A110 | 264 hrs | 4/14/15 |
| Unbiased Highly Accelerated Stress Test | 110C, 85%RH, | JESD22-A118 | 264 hrs | 4/7/15 |
| Temperature Cycle | -40C, 125C | JESD22-A104 | 850 Cycles | 4/27/15 |
| HTOL | 150C, 24V | JESD22-A108 | 500 hrs | 4/17/15 |
| High Temperature storage life | 150 C | JESD22-A103 | 500 hrs | 4/17/15 |

| Qualification Plan | Device | Package | Process | No. of Lots |
|--------------------|------------|-----------|-------------------------------|-------------|
| Q20140424 | FPF2488UCX | UCBBU-015 | SSMC C18BCD gen 2 ASE/Cebu | 1 |

| Test Description: | Condition: | Standard : | Duration: | Results: |
|---|-------------------|-------------|------------|----------|
| Highly Accelerated Stress Test | 110C, 85%RH, 5.7V | JESD22-A110 | 264 hrs | 5/5/15 |
| Unbiased Highly Accelerated Stress Test | 110C, 85%RH, | JESD22-A118 | 264 hrs | 5/5/15 |
| Temperature Cycle | -40C, 125C | JESD22-A104 | 850 Cycles | 5/11/15 |
| HTOL | 150C, 9V/4.4V | JESD22-A108 | 500 hrs | 4/30/15 |
| High Temperature storage life | 150 C | JESD22-A103 | 500 hrs | 4/30/15 |

Appendix A: Changed Products

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PCN Number : P53AAAB

Customer Name :

| Product | Customer Part Number | BBB | Drawing |
|------------------|-----------------------------|------------|----------------|
| FPF2280BUCX_F130 | | Y | N |

Appendix A: Changed Products

PCN Number : P53AAAB

Customer Name :

| Product | Customer Part Number | BBB | Drawing |
|----------------|-----------------------------|------------|----------------|
| FPF2488UCX | | Y | N |